## technical data



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## MOLD WIZ INT-1882

**General:** A process aid additive and mold release which is incorporated directly into the resin eliminating the need for an external mold release agent. Improves resin flow and line speeds. An effective addition of process aid additive will not have any adverse effect on the cured resin. The complex polymeric nature of the process aid additive will not interfere with secondary operations such as decorating, silk screen printing, painting, bonding or plating. Mix well before use.

Use: Various functionality Epoxy systems (Bisphenol A, F etc.) with various curing agents: acid/anhydride, imidazole, amine.

**Composition:** Proprietary synergistic blend of organic fatty esters and amides, combined with surface active agents.

## **TYPICAL PROPERTIES:**

EFFECTIVE INGREDIENTS:	100%
COLOR:	Yellow
SPECIFIC GRAVITY:	0.94 @ 25°C
VISCOSITY:	<300 cps @ 25°C
рН:	6.6
FLASH POINT:	>300°F / >149°C (C.O.C.)
SHELF LIFE:	Minimum of one year

## **Application Instructions:**

General: For best results, laboratory tests or pre-production trials should determine the optimum addition level. MoldWiz process aid additives are effective within a range of 1 to 20 parts per 1000 resin by weight, excluding reinforcements, pigments and fillers. High amounts of filler and/or different processing conditions may require a higher percentage of process aid additives than the indicated maximum. Start an evaluation at 15 parts per 1000 (1.5%) and reduce the loading level if resin viscosity decreases too far for the process and causes excessive slippage. For additional information, refer to Process Aid Additives / Thermoset Resins – Testing Procedures.

**Mixing:** For two-part thermoset resins, mix the process aid additive in the less viscous or less reactive side before catalyzing.

All information given by us about our products is based upon our tests and experience. It is intended for use by persons having technical skill at their own discretion and risk, and we assume no liability in connection with their use.

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